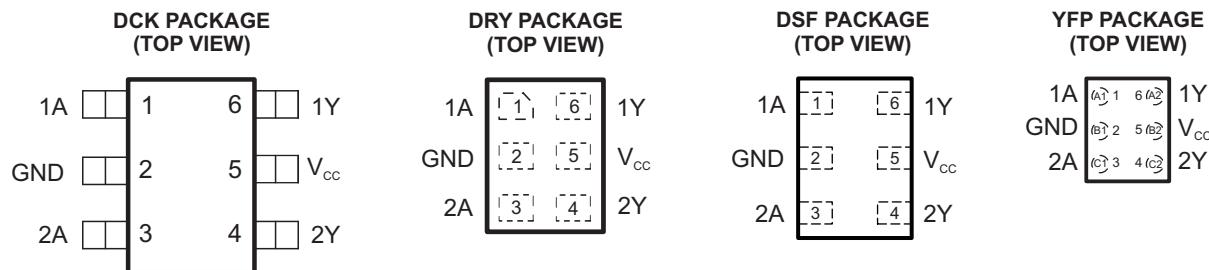


## LOW-POWER DUAL INVERTER GATE

Check for Samples: [SN74AUP2G04](#)

### FEATURES

- Available in the Texas Instruments NanoStar™ Package
- Low Static-Power Consumption:  
 $I_{cc} = 0.9 \mu\text{A}$  Max
- Low Dynamic-Power Consumption:  
 $C_{pd} = 4.3 \text{ pF}$  Typ at 3.3 V
- Low Input Capacitance:  $C_i = 1.5 \text{ pF}$  Typ
- Low Noise: Overshoot and Undershoot <10% of  $V_{cc}$
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Wide Operating  $V_{cc}$  Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 4.3 \text{ ns}$  Max at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

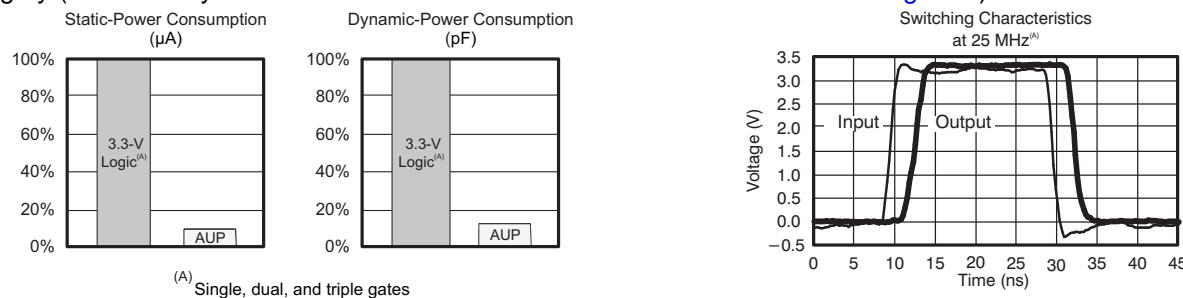
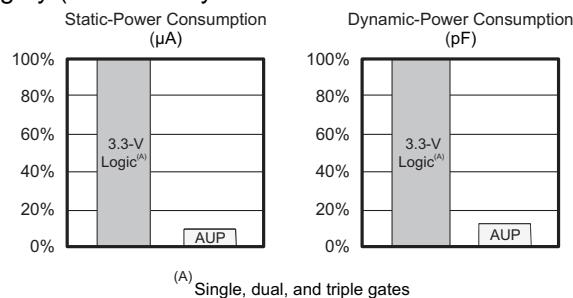


N.C. – No internal connection

See mechanical drawings for dimensions.

### DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire  $V_{cc}$  range of 0.8 V to 3.6 V, resulting in increased battery life (see [Figure 1](#)). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in [Figure 2](#)).



<sup>(A)</sup> SN74AUP2Gxx data at  $C_L = 15 \text{ pF}$ .

**Figure 1. AUP – The Lowest-Power Family**

The SN74AUP2G04 performs the Boolean function  $Y = \bar{A}$  in positive logic.

**Figure 2. Excellent Signal Integrity**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### ORDERING INFORMATION<sup>(1)</sup>

T <sub>A</sub>	PACKAGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
–40°C to 85°C	NanoStar™ – W CSP (DSBGA) 0.23-mm Large Bump – YFP (Pb-free)	Reel of 3000	SN74AUP2G04YFPR _ _ _ H C _
	QFN – DRY	Reel of 5000	SN74AUP2G04DRYR H4
	uQFN – DSF	Reel of 5000	SN74AUP2G04DSFR H4
	SOT (SC-70) – DCK	Reel of 3000	SN74AUP2G04DCKR H4_

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

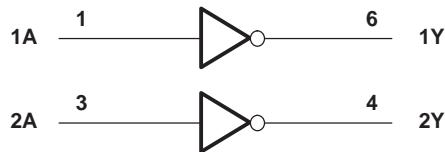
(3) DCK: The actual top-side marking has one additional character that designates the wafer fab/assembly site.

YFP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

### FUNCTION TABLE (Each Inverter)

INPUT A	OUTPUT Y
H	L
L	H

### LOGIC DIAGRAM (POSITIVE LOGIC)



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	4.6	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	4.6	V
$V_O$	Output voltage range in the high or low state <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$	-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$	-50	mA
$I_O$	Continuous output current		$\pm 20$	mA
	Continuous current through $V_{CC}$ or GND		$\pm 50$	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DCK package	252	°C/W
		DRY package	234	
		DSF package	300	
		YFP package	132	
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		0.8	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 0.8 \text{ V}$	$V_{CC}$		V
		$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 0.8 \text{ V}$	0		V
		$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	$0.35 \times V_{CC}$		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0.7		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	0.9		
$V_I$	Input voltage		0	3.6	V
$V_O$	Output voltage		0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 0.8 \text{ V}$	-20		$\mu\text{A}$
		$V_{CC} = 1.1 \text{ V}$	-1.1		
		$V_{CC} = 1.4 \text{ V}$	-1.7		
		$V_{CC} = 1.65 \text{ V}$	-1.9		
		$V_{CC} = 2.3 \text{ V}$	-3.1		
		$V_{CC} = 3 \text{ V}$	-4		
$I_{OL}$	Low-level output current	$V_{CC} = 0.8 \text{ V}$	20		$\mu\text{A}$
		$V_{CC} = 1.1 \text{ V}$	1.1		
		$V_{CC} = 1.4 \text{ V}$	1.7		
		$V_{CC} = 1.65 \text{ V}$	1.9		
		$V_{CC} = 2.3 \text{ V}$	3.1		
		$V_{CC} = 3 \text{ V}$	4		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	200		ns/V
$T_A$	Operating free-air temperature		-40	85	°C

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -20 µA	0.8 V to 3.6 V	V <sub>CC</sub> - 0.1			V <sub>CC</sub> - 0.1		V
	I <sub>OH</sub> = -1.1 mA	1.1 V	0.75 × V <sub>CC</sub>			0.7 × V <sub>CC</sub>		
	I <sub>OH</sub> = -1.7 mA	1.4 V	1.11			1.03		
	I <sub>OH</sub> = -1.9 mA	1.65 V	1.32			1.3		
	I <sub>OH</sub> = -2.3 mA	2.3 V	2.05			1.97		
	I <sub>OH</sub> = -3.1 mA		1.9			1.85		
	I <sub>OH</sub> = -2.7 mA	3 V	2.72			2.67		
	I <sub>OH</sub> = -4 mA		2.6			2.55		
V <sub>OL</sub>	I <sub>OL</sub> = 20 µA	0.8 V to 3.6 V		0.1			0.1	V
	I <sub>OL</sub> = 1.1 mA	1.1 V		0.3 × V <sub>CC</sub>			0.3 × V <sub>CC</sub>	
	I <sub>OL</sub> = 1.7 mA	1.4 V		0.31			0.37	
	I <sub>OL</sub> = 1.9 mA	1.65 V		0.31			0.35	
	I <sub>OL</sub> = 2.3 mA	2.3 V		0.31			0.33	
	I <sub>OL</sub> = 3.1 mA			0.44			0.45	
	I <sub>OL</sub> = 2.7 mA	3 V		0.31			0.33	
	I <sub>OL</sub> = 4 mA			0.44			0.45	
I <sub>I</sub>	A or B input	V <sub>I</sub> = GND to 3.6 V	0 V to 3.6 V		0.1		0.5	µA
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V	0 V		0.2		0.6	µA
ΔI <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V	0 V to 0.2 V		0.2		0.6	µA
I <sub>CC</sub>	V <sub>I</sub> = GND or (V <sub>CC</sub> to 3.6 V), I <sub>O</sub> = 0	0.8 V to 3.6 V		0.5			0.9	µA
ΔI <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V <sup>(1)</sup> , I <sub>O</sub> = 0	3.3 V		40			50	µA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	0 V		1.5				pF
		3.6 V		1.5				
C <sub>o</sub>	V <sub>O</sub> = GND	0 V		3				pF

(1) One input at V<sub>CC</sub> - 0.6 V, other input at V<sub>CC</sub> or GND.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, C<sub>L</sub> = 5 pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	0.8 V		18				ns
			1.2 V ± 0.1 V	2.6	7.3	12.8	2.1	15.6	
			1.5 V ± 0.1 V	1.4	5.2	8.7	0.9	10.3	
			1.8 V ± 0.15 V	1	4.2	6.6	0.5	8.2	
			2.5 V ± 0.2 V	1	3	4.4	0.5	5.5	
			3.3 V ± 0.3 V	1	2.4	3.5	0.5	4.3	

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,  $C_L = 10 \text{ pF}$  (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	0.8 V		21				ns
			1.2 V $\pm 0.1$ V	1.5	8.5	14.7	1	17.2	
			1.5 V $\pm 0.1$ V	1	6.2	10	0.5	11.3	
			1.8 V $\pm 0.15$ V	1	5	7.7	0.5	9	
			2.5 V $\pm 0.2$ V	1	3.6	5.2	0.5	6.1	
			3.3 V $\pm 0.3$ V	1	2.9	4.2	0.5	4.7	

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	0.8 V		24				ns
			1.2 V $\pm 0.1$ V	3.6	9.9	16.3	3.1	19.9	
			1.5 V $\pm 0.1$ V	2.3	7.2	11.1	1.8	13.2	
			1.8 V $\pm 0.15$ V	1.6	5.8	8.7	1.1	10.6	
			2.5 V $\pm 0.2$ V	1	4.3	5.9	0.5	7.3	
			3.3 V $\pm 0.3$ V	1	3.4	4.8	0.5	5.9	

## SWITCHING CHARACTERISTICS

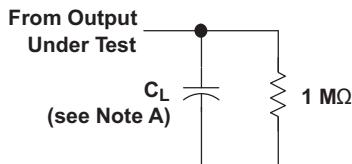
over recommended operating free-air temperature range,  $C_L = 30 \text{ pF}$  (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	0.8 V		32.8				ns
			1.2 V $\pm 0.1$ V	4.9	13.1	20.9	4.4	25.5	
			1.5 V $\pm 0.1$ V	3.4	9.5	14.2	2.9	16.9	
			1.8 V $\pm 0.15$ V	2.5	7.7	11	2	13.5	
			2.5 V $\pm 0.2$ V	1.8	5.7	7.6	1.3	9.4	
			3.3 V $\pm 0.3$ V	1.5	4.7	6.2	1	7.5	

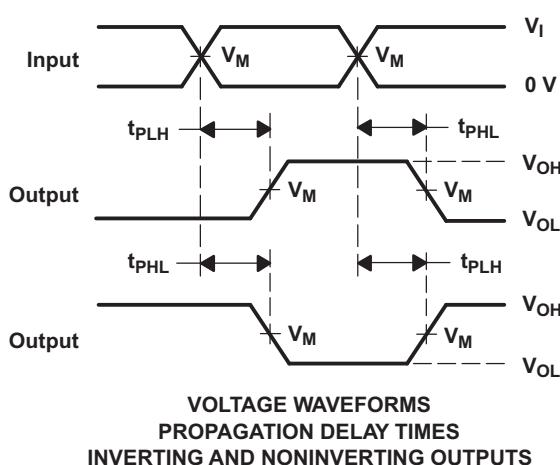
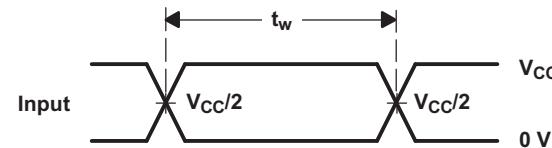
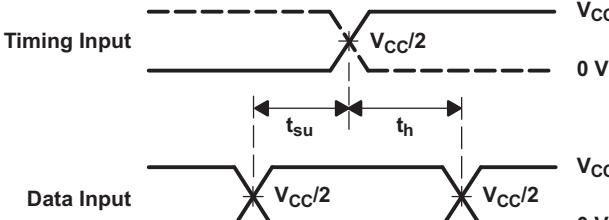
## OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS			$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	$f = 10 \text{ MHz}$	0.8 V		0.8 V	4	pF
			1.2 V $\pm 0.1$ V		1.2 V $\pm 0.1$ V	4	
			1.5 V $\pm 0.1$ V		1.5 V $\pm 0.1$ V	4	
			1.8 V $\pm 0.15$ V		1.8 V $\pm 0.15$ V	4	
			2.5 V $\pm 0.2$ V		2.5 V $\pm 0.2$ V	4.1	
			3.3 V $\pm 0.3$ V		3.3 V $\pm 0.3$ V	4.3	

**PARAMETER MEASUREMENT INFORMATION  
(Propagation Delays, Setup and Hold Times, and Pulse Width)**

**LOAD CIRCUIT**

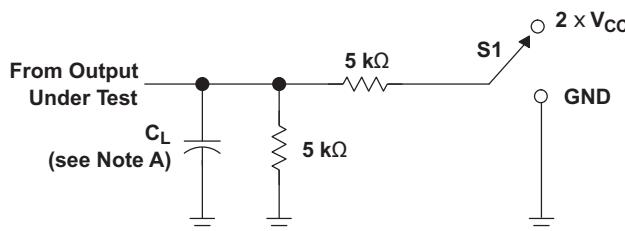
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$


**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS  
PULSE DURATION**

**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ , for propagation delays  $t_r/t_f = 3 \text{ ns}$ , for setup and hold times and pulse width  $t_r/t_f = 1.2 \text{ ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- F. All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**

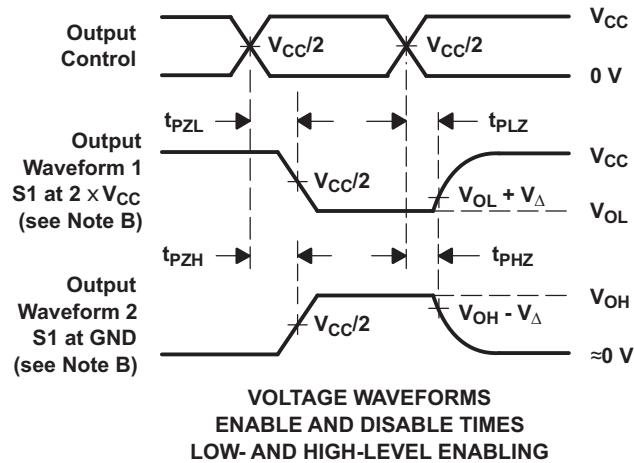
### PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



TEST	S1
$t_{PLZ}/t_{PZL}$	2 x V <sub>CC</sub>
$t_{PHZ}/t_{PZH}$	GND

LOAD CIRCUIT

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$
$V_\Delta$	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r/t_f = 3 \text{ ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74AUP2G04DCKR</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	(H45, H4F)
SN74AUP2G04DCKR.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(H45, H4F)
SN74AUP2G04DCKRG4	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4F
SN74AUP2G04DCKRG4.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4F
<a href="#">SN74AUP2G04DRYR</a>	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H4
SN74AUP2G04DRYR.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H4
SN74AUP2G04DRYRG4	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4
SN74AUP2G04DRYRG4.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4
<a href="#">SN74AUP2G04DSFR</a>	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H4
SN74AUP2G04DSFR.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4
SN74AUP2G04DSFRG4	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4
SN74AUP2G04DSFRG4.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H4
<a href="#">SN74AUP2G04YFPR</a>	Active	Production	DSBGA (YFP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HCN
SN74AUP2G04YFPR.B	Active	Production	DSBGA (YFP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HCN

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

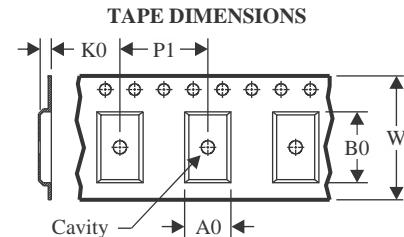
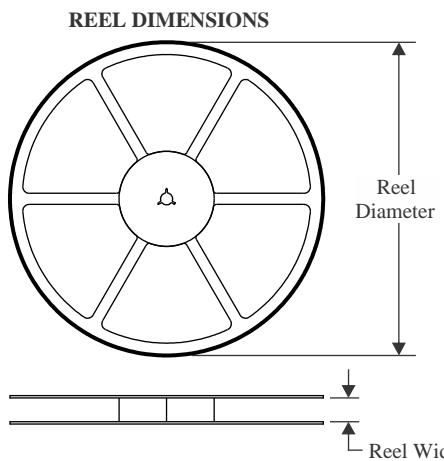
<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

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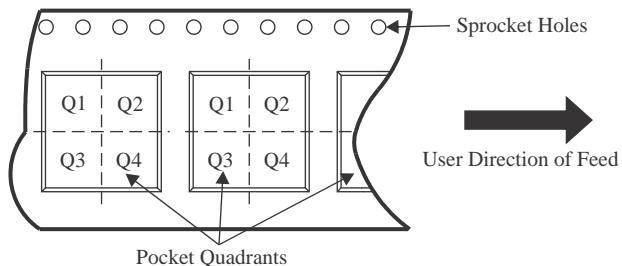
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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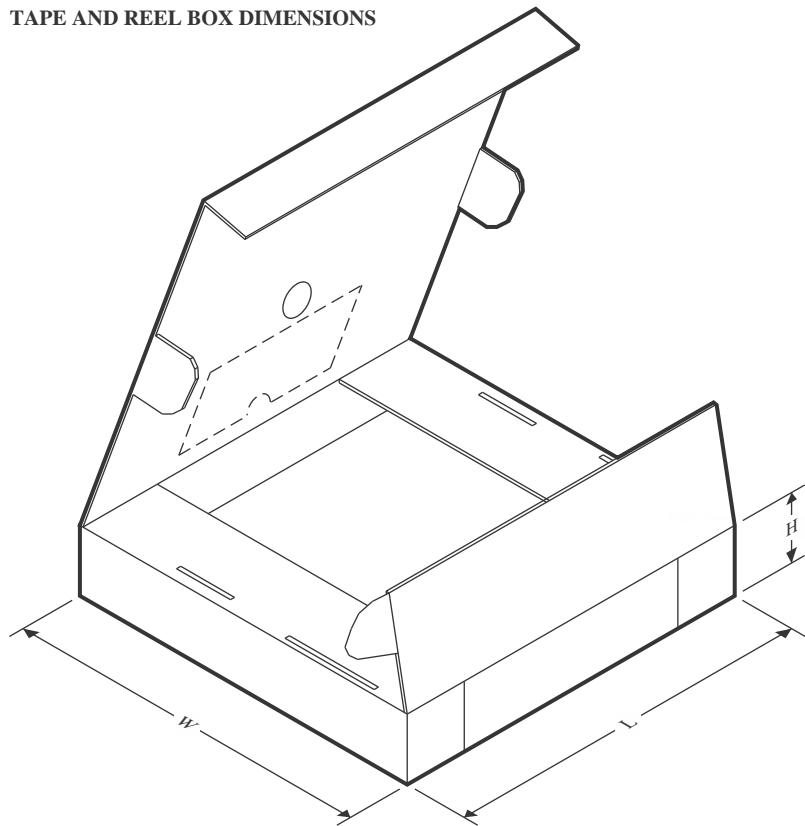
**TAPE AND REEL INFORMATION**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP2G04DCKR	SC70	DCK	6	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
SN74AUP2G04DCKRG4	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AUP2G04DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP2G04DRYRG4	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP2G04DSFR	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP2G04DSFRG4	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP2G04YFPR	DSBGA	YFP	6	3000	178.0	9.2	0.89	1.29	0.62	4.0	8.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP2G04DCKR	SC70	DCK	6	3000	210.0	185.0	35.0
SN74AUP2G04DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74AUP2G04DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP2G04DRYRG4	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP2G04DSFR	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G04DSFRG4	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G04YFPR	DSBGA	YFP	6	3000	220.0	220.0	35.0

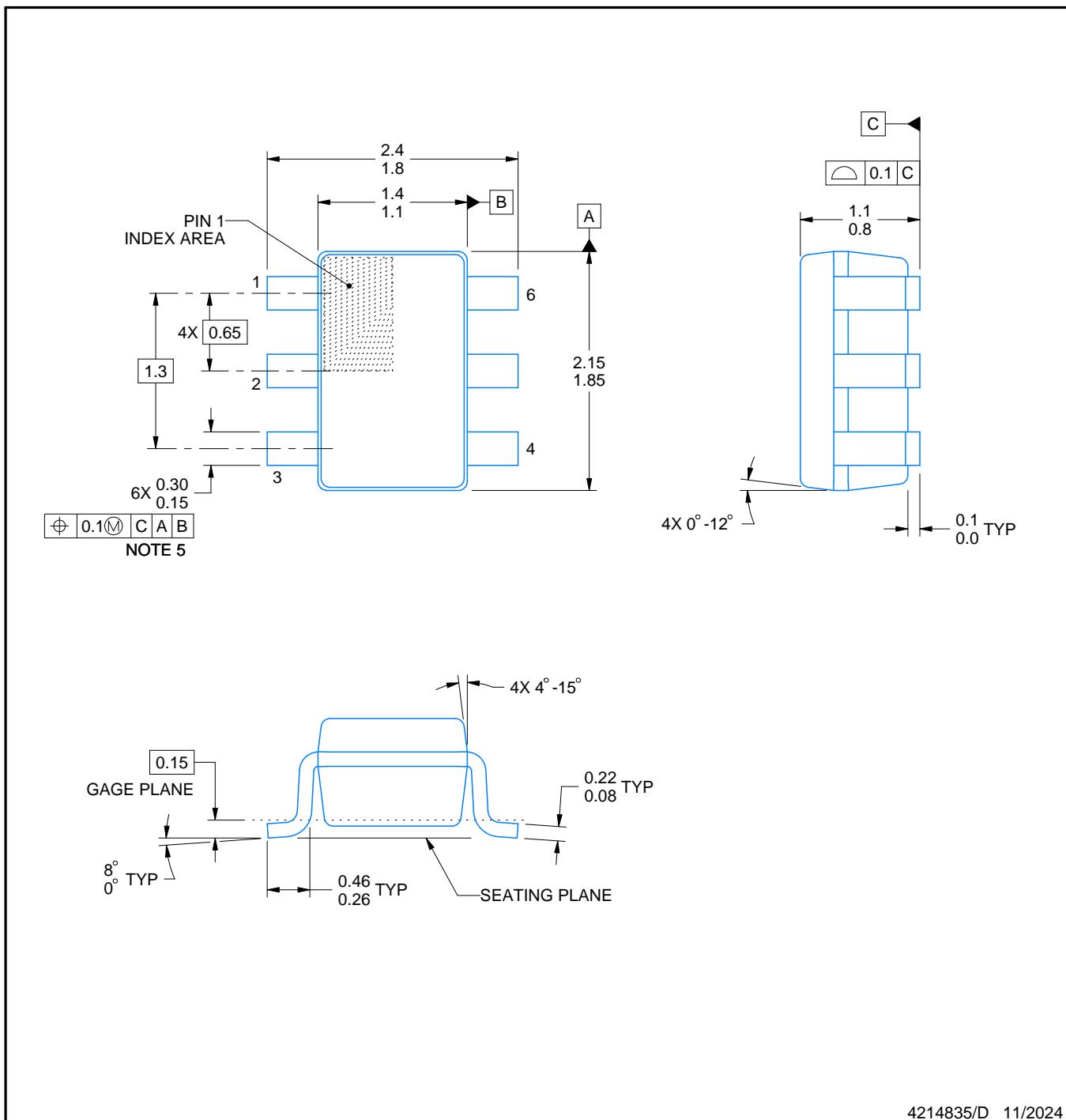
# PACKAGE OUTLINE

DCK0006A



SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



4214835/D 11/2024

## NOTES:

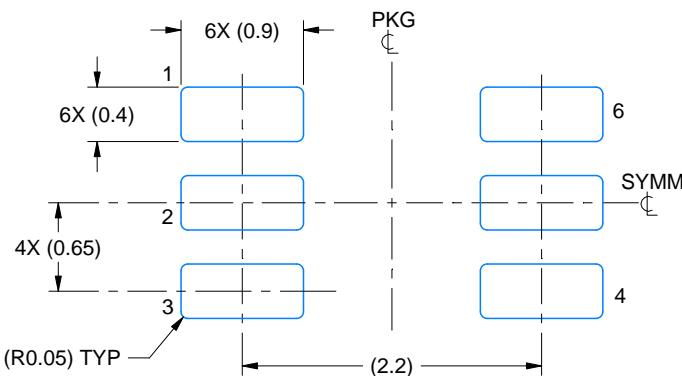
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
4. Falls within JEDEC MO-203 variation AB.

# EXAMPLE BOARD LAYOUT

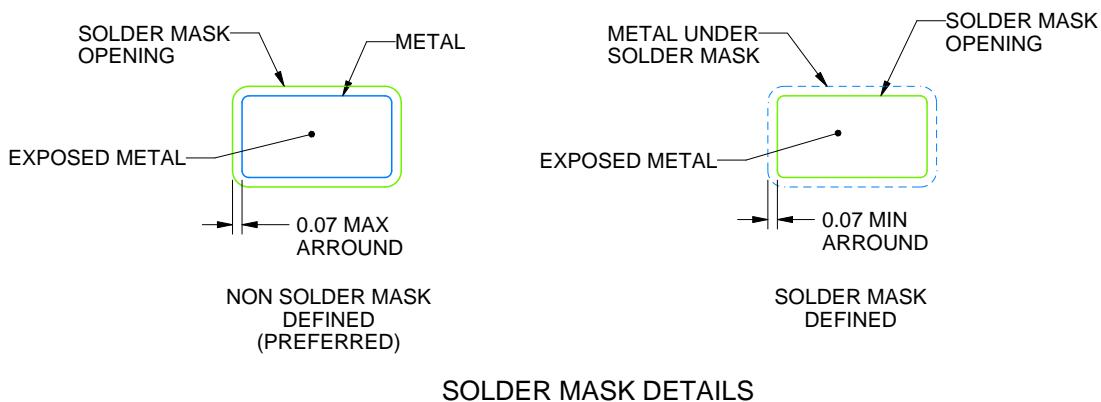
DCK0006A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



4214835/D 11/2024

NOTES: (continued)

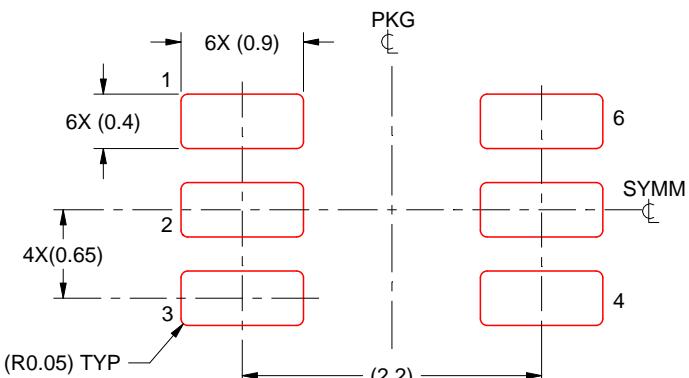
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0006A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214835/D 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DRY 6

## GENERIC PACKAGE VIEW

### USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4207181/G

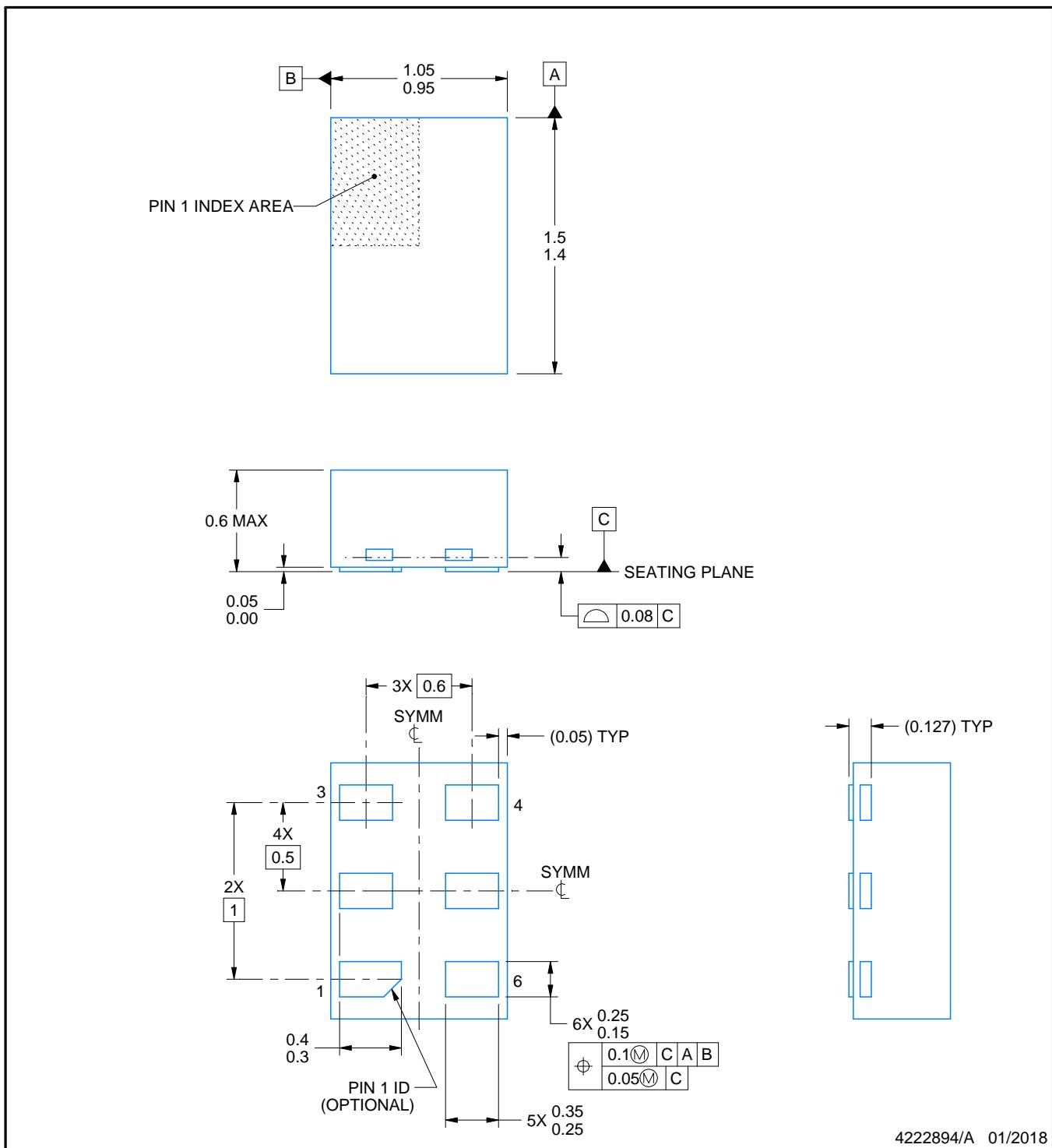
# PACKAGE OUTLINE

DRY0006A



USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4222894/A 01/2018

## NOTES:

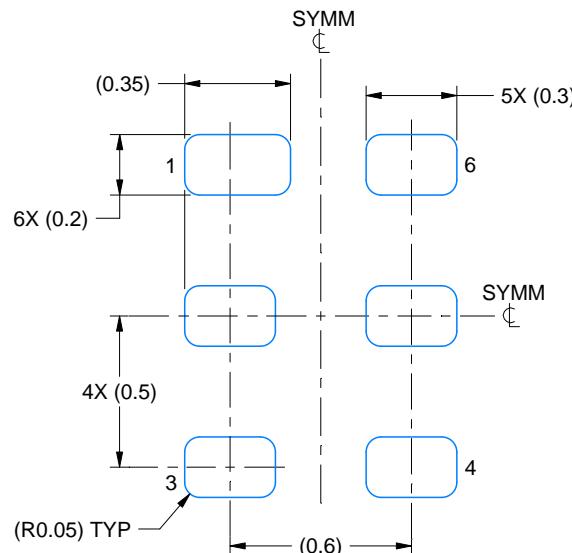
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

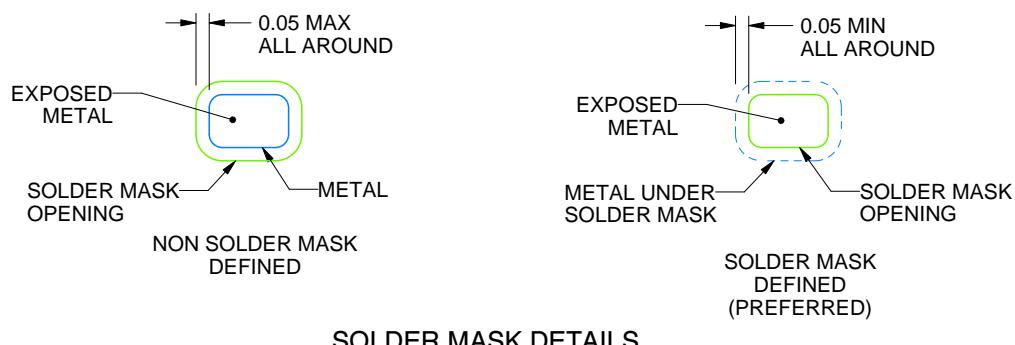
DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
1:1 RATIO WITH PKG SOLDER PADS  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

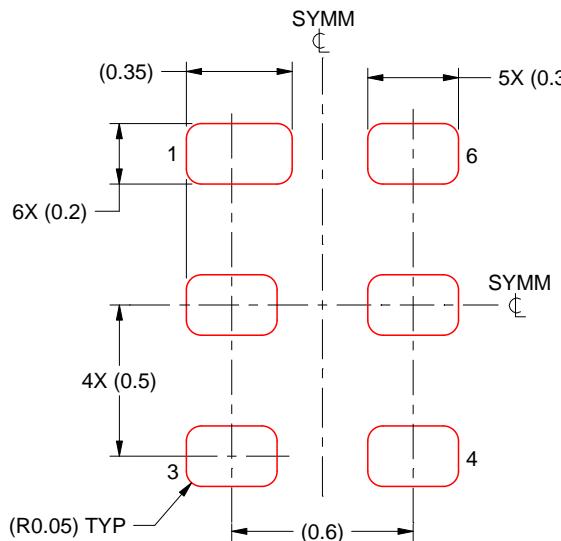
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.075 - 0.1 mm THICK STENCIL  
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

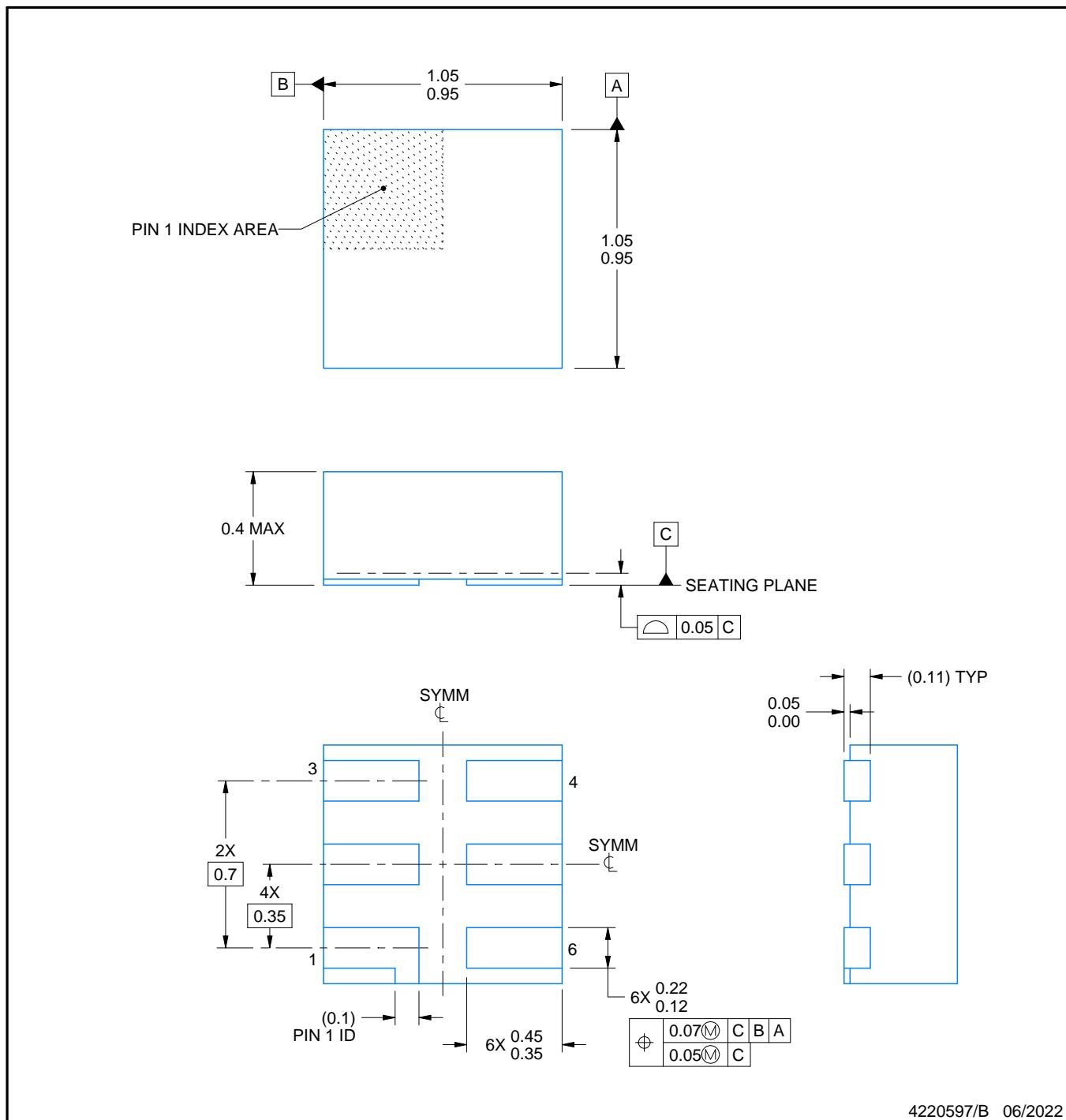


## PACKAGE OUTLINE

**DSF0006A**

## **X2SON - 0.4 mm max height**

## PLASTIC SMALL OUTLINE - NO LEAD



4220597/B 06/2022

## NOTES:

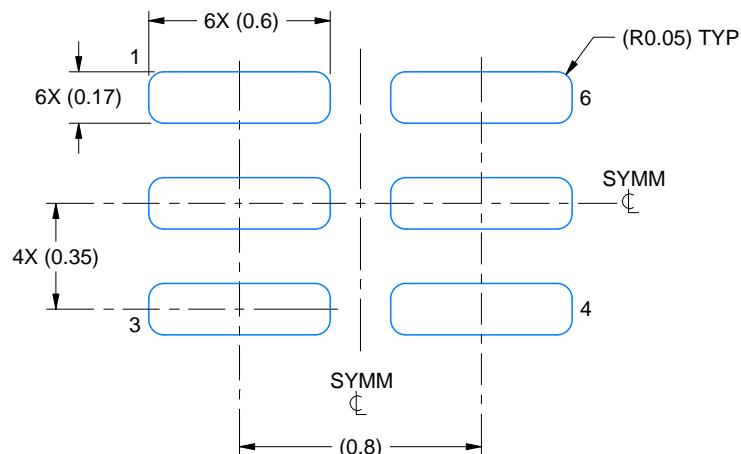
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

# EXAMPLE BOARD LAYOUT

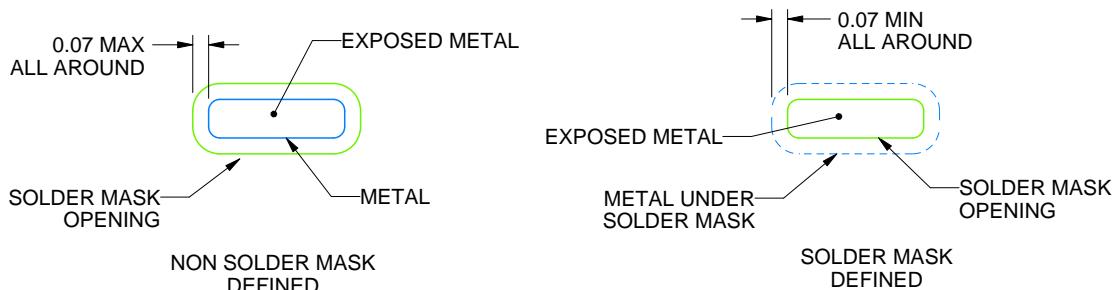
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4220597/B 06/2022

NOTES: (continued)

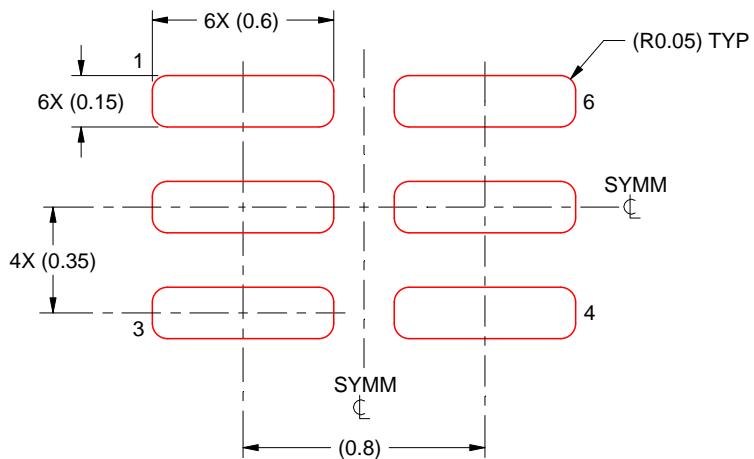
4. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.09 mm THICK STENCIL

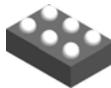
PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:40X

4220597/B 06/2022

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

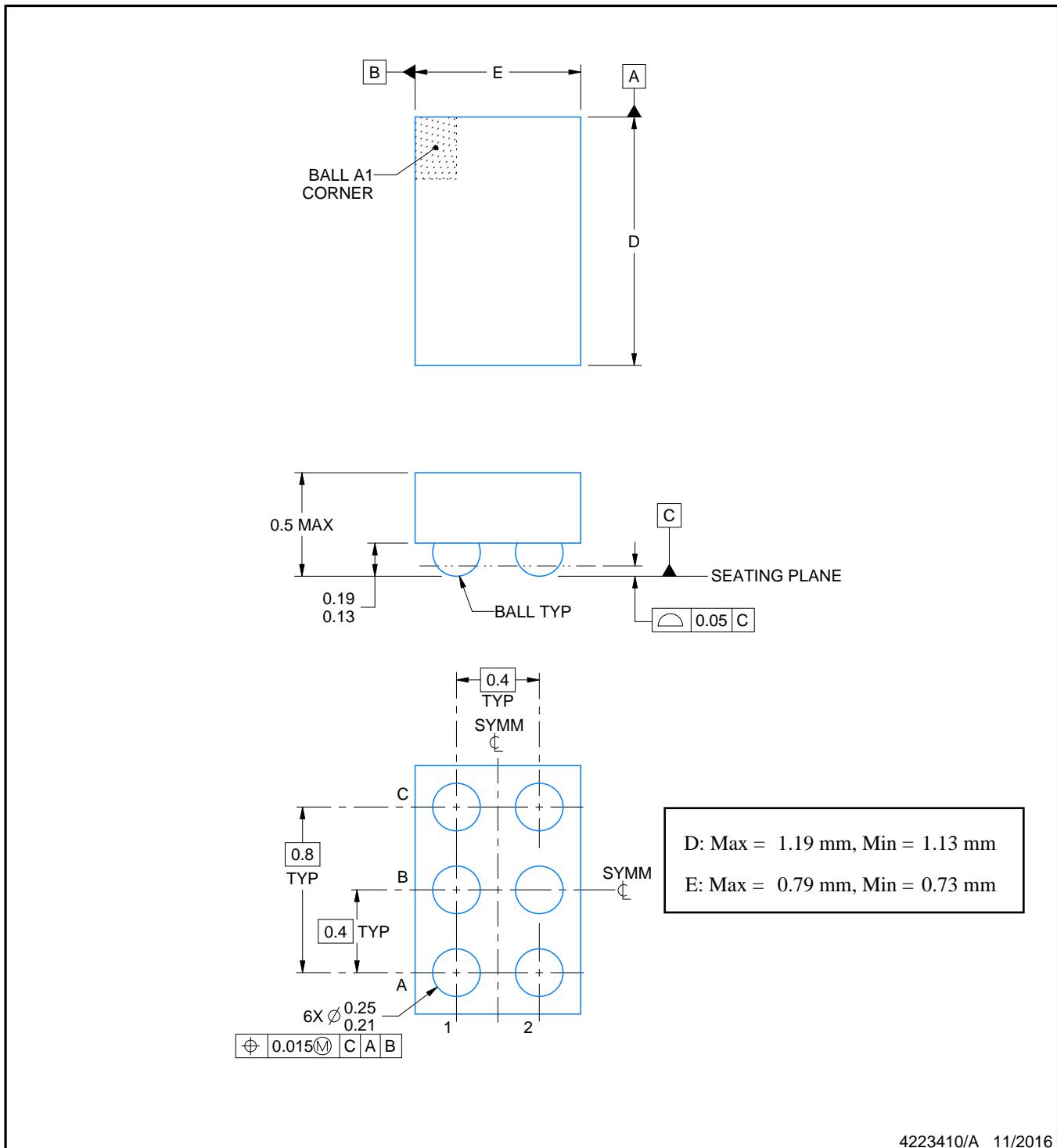
# PACKAGE OUTLINE

**YFP0006**



**DSBGA - 0.5 mm max height**

DIE SIZE BALL GRID ARRAY



4223410/A 11/2016

**NOTES:**

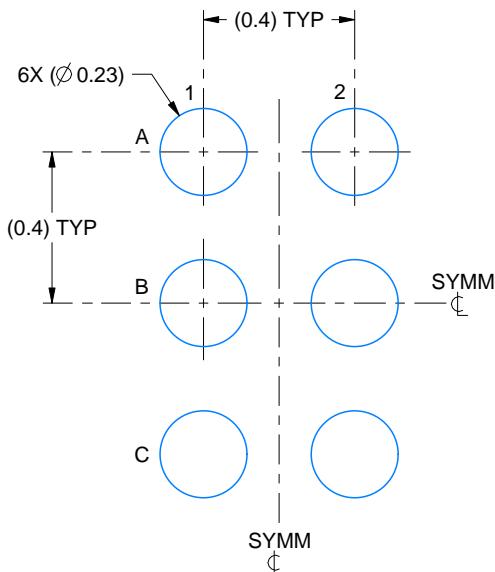
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

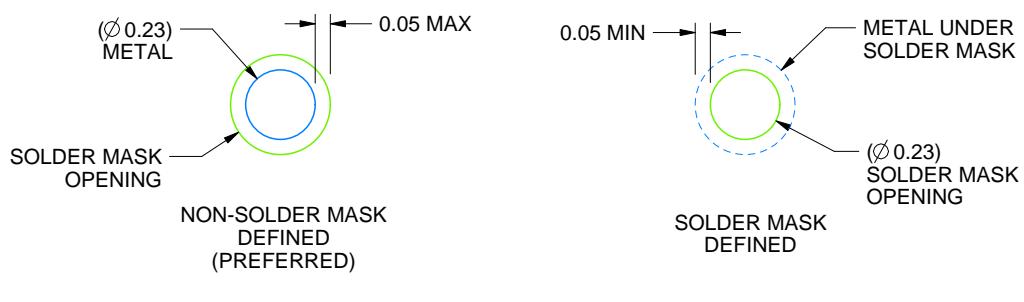
YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:50X



SOLDER MASK DETAILS  
NOT TO SCALE

4223410/A 11/2016

NOTES: (continued)

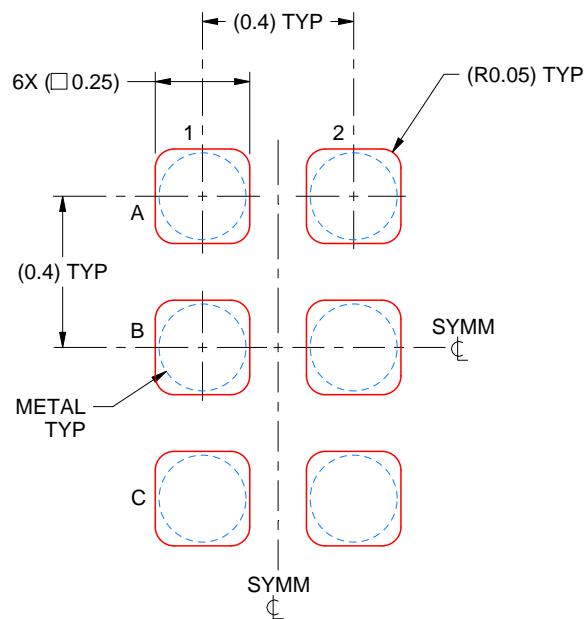
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.  
For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:50X

4223410/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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